

Class AB Stereo Headphone Driver

Features

- Operating Voltage
 - Single Supply 3V to 6V
 - Dual Supply $\pm 1.5V$ to $\pm 3.0V$
- High Signal-to-Noise Ratio 100dB
- Low Distortion -65dB
- Large Output Voltage Swing
- Excellent Power Supply Ripple Rejection
- Low Power Consumption
- Short-circuit Elimination
- Wide Temperature Range
- No Switch ON/OFF Clicks
- Available in 8 pin SOP ,DIP or TSSOP Package

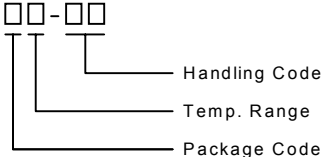
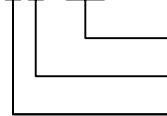

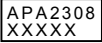
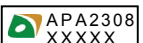
Applications

- Portable Digital Audio

General Description

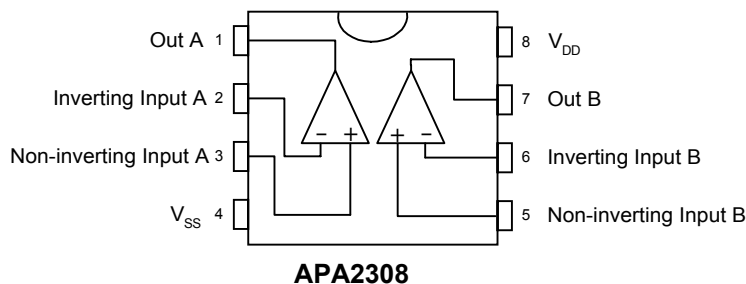
The APA2308 is an integrated class AB stereo headphone driver contained in an SO-8, a DIP-8 or a TSSOP-8 plastic package. The APA2308 is capable of delivering 280mW of max. Output power to an 8 Ω load or 110mW to a 32 Ω load with less than 10% (THD+N) from a 5V power supply. The device is fabricated in a CMOS process and has been primarily developed for portable digital audio applications .

Ordering and Marking Information

APA2308 	 <ul style="list-style-type: none"> Handling Code Temp. Range Package Code 	Package Code J : PDIP - 8 K : SOP - 8 O : TSSOP - 8 Temp. Range I : - 40 to 85° C Handling Code TU : Tube TR : Tape & Reel
APA2308 J :		XXXXX - Date Code
APA2308 K :		XXXXX - Date Code
APA2308 O :		XXXXX - Date Code

ANPEC reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

Block Diagram



Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
V_{DD}	Supply Voltage	7	V
$T_{SC(O)}$	Output Short-circuit Duration, at $T_A=25^{\circ}C$, $P_{TOT}=1W$	20	S
T_A	Operating Ambient Temperature range	-40 to 85	$^{\circ}C$
T_J	Maximum Junction Temperature	150	$^{\circ}C$
T_{STG}	Storage Temperature Range	-65 to +150	$^{\circ}C$
T_S	Soldering Temperature , 10 seconds	260	$^{\circ}C$
V_{ESD}	Electrostatic Discharge	-3000 to 3000*1	V

Note : *1. Human body model : $C=100pF$, $R=1500\Omega$, 3 positive pulses plus 3 negative pulses

Thermal Characteristics

Symbol	Parameter	Value	Unit
R_{THJA}	Thermal Resistance from Junction to Ambient in Free Air		
	DIP-8	109	K/W
	SO-8	210	K/W

Electrical Characteristics

$V_{DD}=5V$, $V_{SS}=0V$, $T_A=25^{\circ}C$, $f_i=1kHz$, $R_L=32\Omega$ (unless otherwise noted)

Symbol	Parameter	Test Condition	APA2308			Unit
			Min.	Typ.	Max	
Supply						
V_{DD}	Supply Voltage					V
	Single		3.0	5.0	6.0	
	Dual		± 1.5	± 2.5	± 3.0	
V_{SS}	Negative Supply Voltage		-1.5	-2.5	-3.0	V
I_{DD}	Supply Current	No Load		2.5	5	MA
P_{TOT}	Total Power Dissipation	No Load		12.5	25	mW

Electrical Characteristics Cont.

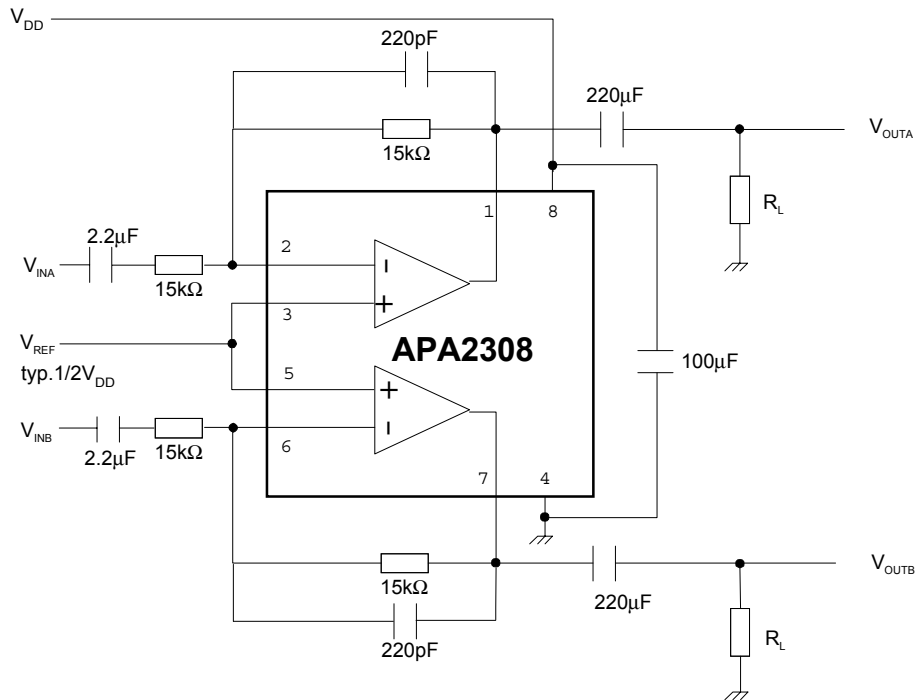
$V_{DD}=5V$, $V_{SS}=0V$, $T_A=25^{\circ}C$, $f_i=1kHz$, $R_L=32\Omega$ (unless otherwise noted)

Symbol	Parameter	Test Condition	APA2308			Unit
			Min.	Typ.	Max	
DC Characteristics						
$V_{I(OS)}$	Input Offset Voltage			5		MV
I_{BIAS}	Input Bias Current			10		PA
V_{CM}	Common Mode Voltage		0		3.5	V
G_V	Open-loop Voltage Gain	$R_L=5k\Omega$		75		dB
I_O	Max. Output Current	$(THD+N)/S < 0.1\%$		140		MA
R_O	Output Resistance			0.25		Ω
AC Characteristics						
V_O	Output Voltage Swing	$R_L=32\Omega^{*1}$	0.25		4.75	V
		$R_L=16\Omega^{*1}$	0.5		4.5	
PSRR	Power Supply Rejection Ratio	$F_i=100Hz$ $V_{RIPPLE(P-P)}=100mV$		65		dB
α_{CS}	Channel Separation	$R_L=32\Omega$		95		dB
C_L	Load Capacitance				200	pF
(THD+N)/S	Total Harmonic Distortion Plus Noise to Signal Ratio	$R_L=32\Omega^{*2}$		-65	-60	dB
				0.05	0.1	%
S/N	Signal to Noise Ratio		90	100		dB
F_G	Unity Gain Frequency	$R_L=5k\Omega$		5		MHz
P_O	Max. Output Power	$(THD+N)/S < 0.1\%$		84		mW
C_I	Input Capacitance			3		pF
B	Power Bandwidth	Unity Gain Inverting		20		kHz

Notes *1 : Values are proportional to V_{DD} ; $(THD+N)/S < 0.1\%$

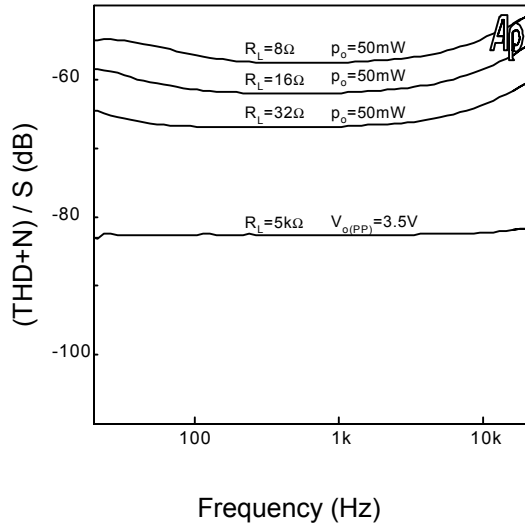
*2 : $V_{DD}=5.0V$; $V_{O(P-P)}=3.5V$ (at 0 dB)

Test And Application Circuits

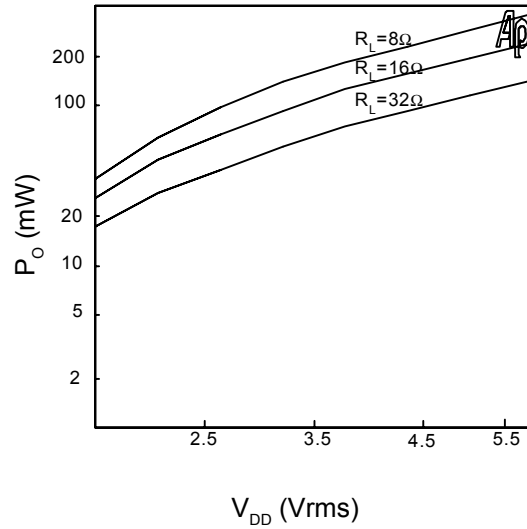


Typical Characteristics

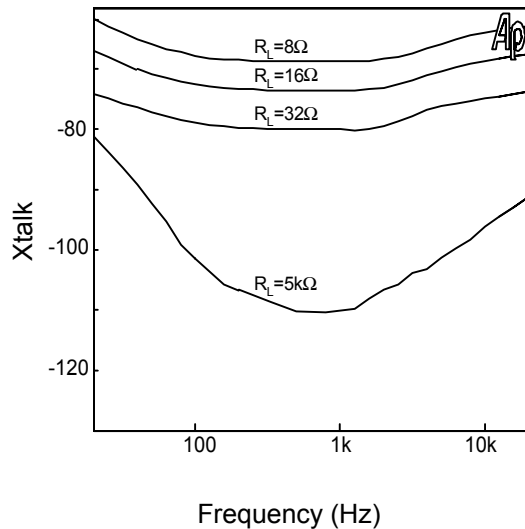
Total Harmonic Distortion Plus Noise-to-Signal Ratio as a Function of Input Frequency



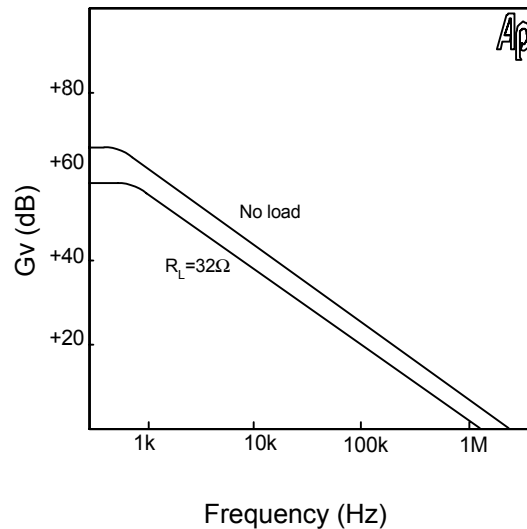
Output Power as a Function of Supply Voltage



Crosstalk as a Function of Input Frequency

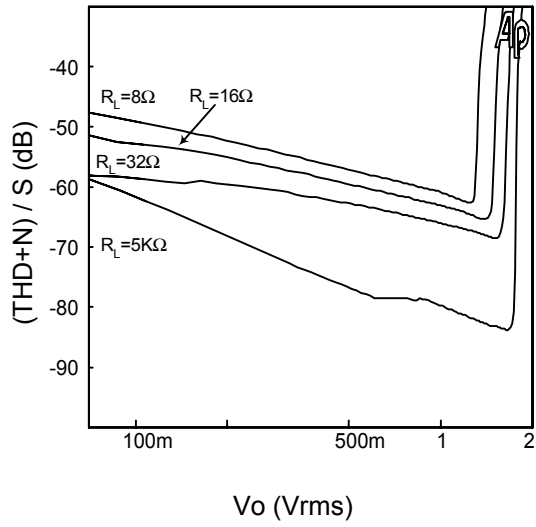


Open Loop Gain as a Function of Input Frequency



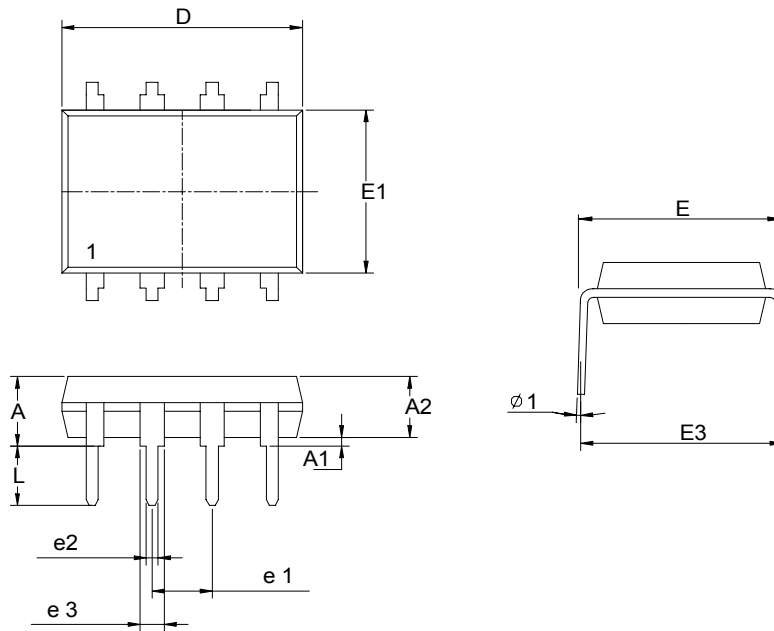
Typical Characteristics Cont.

Total Harmonic Distortion Plus Noise-to-Signal Ratio as a Function of output Voltage



Packaging Information

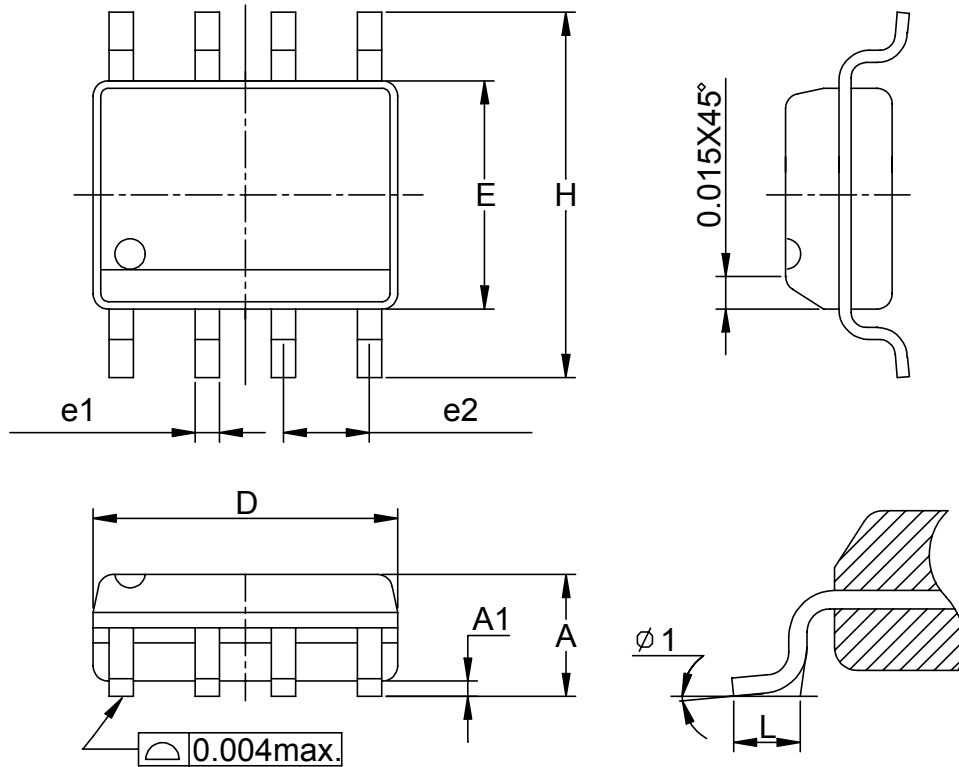
PDIP-8 pin (Reference JEDEC Registration MS-001)



Dim	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A		5.33		0.210
A1	0.38		0.015	
A2	2.92	3.68	0.115	0.145
D	9.02	10.16	0.355	0.400
e1	2.54BSC		0.100BSC	
e2	0.36	0.56	0.014	0.022
e3	1.14	1.78	0.045	0.070
E	7.62 BSC		0.300 BSC	
E1	6.10	7.11	0.240	0.280
E3		10.92		0.430
L	2.92	3.81	0.115	0.150
∅ 1	15°		15°	

Packaging Information

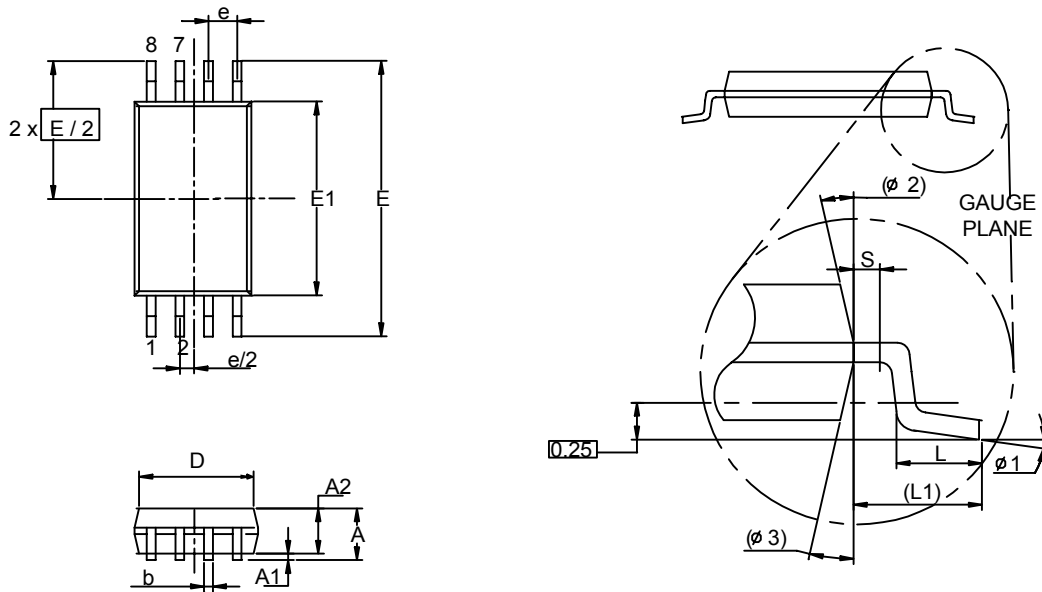
SOP-8 pin (Reference JEDEC Registration MS-012)



Dim	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
D	4.80	5.00	0.189	0.197
E	3.80	4.00	0.150	0.157
H	5.80	6.20	0.228	0.244
L	0.40	1.27	0.016	0.050
e1	0.33	0.51	0.013	0.020
e2	1.27BSC		0.50BSC	
φ 1	8°		8°	

Packaging Information

TSSOP-8



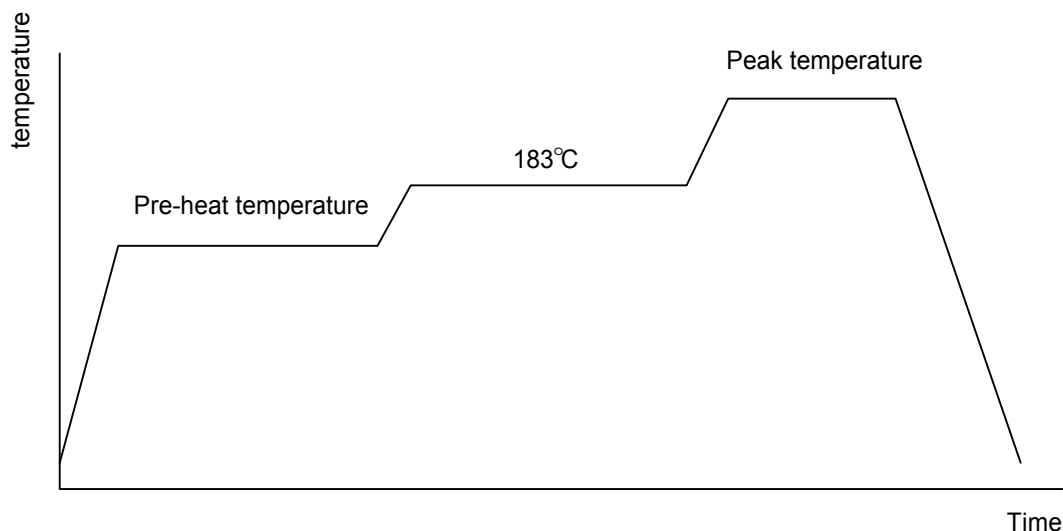
Dim	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A		1.2		0.047
A1	0.00	0.15	0.000	0.006
A2	0.80	1.05	0.031	0.041
b	0.19	0.30	0.007	0.012
D	2.9	3.1	0.114	0.122
e	0.65 BSC		0.026 BSC	
E	6.40 BSC		0.252 BSC	
E1	4.30	4.50	0.169	0.177
L	0.45	0.75	0.018	0.030
L1	1.0 REF		0.039 REF	
R	0.09		0.004	
R1	0.09		0.004	
S	0.2		0.008	
φ1	0°	8°	0°	8°
φ2	12° REF		12° REF	
φ3	12° REF		12° REF	

Physical Specifications

Terminal Material	Solder-Plated Copper (Solder Material : 90/10 or 63/37 SnPb)
Lead Solderability	Meets EIA Specification RSI86-91, ANSI/J-STD-002 Category 3.

Reflow Condition (IR/Convection or VPR Reflow)

Reference JEDEC Standard J-STD-020A APRIL 1999



Classification Reflow Profiles

	Convection or IR/ Convection	VPR
Average ramp-up rate(183°C to Peak)	3°C/second max.	10 °C /second max.
Preheat temperature 125 ± 25°C)	120 seconds max	
Temperature maintained above 183°C	60 – 150 seconds	
Time within 5°C of actual peak temperature	10 –20 seconds	60 seconds
Peak temperature range	220 +5/-0°C or 235 +5/-0°C	215-219°C or 235 +5/-0°C
Ramp-down rate	6 °C /second max.	10 °C /second max.
Time 25°C to peak temperature	6 minutes max.	

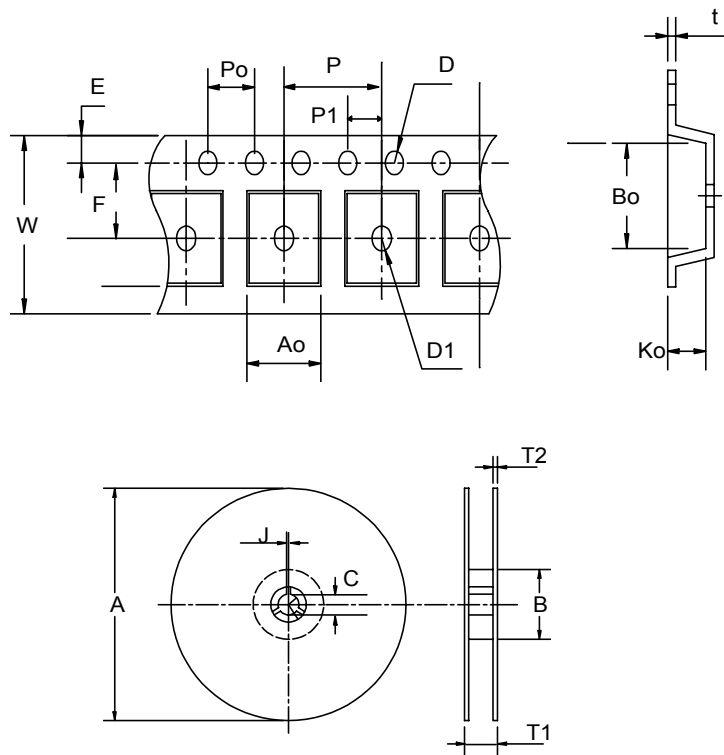
Package Reflow Conditions

pkg. thickness ≥ 2.5mm and all bgas	pkg. thickness < 2.5mm and pkg. volume ≥ 350 mm ³	pkg. thickness < 2.5mm and pkg. volume < 350mm ³
Convection 220 +5/-0 °C		Convection 235 +5/-0 °C
VPR 215-219 °C		VPR 235 +5/-0 °C
IR/Convection 220 +5/-0 °C		IR/Convection 235 +5/-0 °C

Reliability test Program

Test item	Method	Description
SOLDERABILITY	MIL-STD-883D-2003	245° C , 5 SEC
HOLT	MIL-STD-883D-1005.7	1000 Hrs Bias @ 125 °C
PCT	JESD-22-B, A102	168 Hrs, 100 % RH , 121 °C
TST	MIL-STD-883D-1011.9	-65° C ~ 150° C , 200 Cycles
ESD	MIL-STD-883D-3015.7	VHBM > 2KV, VMM > 200V
Latch-Up	JESD 78	10ms , I _{tr} > 100mA

Carrier Tape & Reel Dimensions



Application	A	B	C	J	T1	T2	W	P	E
SOP-8	330 ± 1	62 +1.5	12.75+ 0.15	2 ± 0.5	12.4 ± 0.2	2 ± 0.2	12± 0.3	8± 0.1	1.75±0.1
	F	D	D1	Po	P1	Ao	Bo	Ko	t
	5.5± 1	1.55 +0.1	1.55+ 0.25	4.0 ± 0.1	2.0 ± 0.1	6.4 ± 0.1	5.2± 0.1	2.1± 0.1	0.3±0.013
Application	A	B	C	J	T1	T2	W	P	E
TSSOP-8	330 ± 1	62 +1.5	12.75+ 0.15	2 + 0.5	12.4 ± 0.2	2 ± 0.2	12± 0.3	8± 0.1	1.75±0.1
	F	D	D1	Po	P1	Ao	Bo	Ko	t
	5.5 ± 0.1	1.5 + 0.1	1.5 + 0.1	4.0 ± 0.1	2.0 ± 0.1	7.0 ± 0.1	3.6 ± 0.3	1.6 ± 0.1	0.3±0.013

(mm)

Cover Tape Dimensions

Application	Carrier Width	Cover Tape Width	Devices Per Reel
SOP- 8	12	9.3	2500
TSSOP- 8	12	9.3	2500

Customer Service

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